

ABSTRACT

A semiconductor build-up package includes a die, a metal carrier, and a plurality of dielectric layers. The metal carrier has a surface with a cavity for supporting the die. The surface of metal carrier is coplanar to the active surface of die for building up a plurality of dielectric layers. Each dielectric layer has metal columns for inner electrical connection. The metal carrier covers passive surface and sides of the die with a larger area for heat dissipating, so the heat generated from the die is dissipated fast through the metal carrier.